



Title of Change:	Qualification of ON Semiconductor facility in Carmona, Philippines as an additional Final Test Location for former AXSEM Product AX5051.													
Proposed first ship date:	04 October 2017 <i>or earlier after customer approval</i>													
Contact information:	Contact your local ON Semiconductor Sales Office													
Samples:	Contact your local ON Semiconductor Sales Office													
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office													
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.													
Change Part Identification:	Affected products will be identified with date code.													
Change category:	<input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input checked="" type="checkbox"/> Test Change <input type="checkbox"/> Other _____													
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Material Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Shipping/Packaging/Marking <input checked="" type="checkbox"/> Other: Tester Equipment Change													
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Carmona, Philippines <input type="checkbox"/> External Foundry/Subcon site(s)													
Description and Purpose:														
AXSEM AG was acquired by ON Semiconductor in July, 2015. To expand probe capacity, ON Semiconductor Carmona, Philippines will be added as a final test location for the below mentioned devices.														
<table border="1"> <thead> <tr> <th>Changes</th> <th>Before Change Description</th> <th>After Change Description</th> </tr> </thead> <tbody> <tr> <td>Tester Platform</td> <td>Ocelot Inovys</td> <td>uFlex Analog/Full</td> </tr> <tr> <td>Tester Flow</td> <td>Ambient Only</td> <td>Ambient and QC Ambient</td> </tr> <tr> <td>Carrier Tape</td> <td>CPAK(BGA0505 CL3 22X6 L500 W12)</td> <td>CPAK(BGA0505 CL3 22X6 L500 W12)</td> </tr> </tbody> </table>			Changes	Before Change Description	After Change Description	Tester Platform	Ocelot Inovys	uFlex Analog/Full	Tester Flow	Ambient Only	Ambient and QC Ambient	Carrier Tape	CPAK(BGA0505 CL3 22X6 L500 W12)	CPAK(BGA0505 CL3 22X6 L500 W12)
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Reliability Data Summary: Reliability Data can be made available upon request.														
Electrical Characteristic Summary: Electrical Correlation Data can be made available upon request.														
List of Affected Standard Parts:														
Part Number	Qualification Vehicle													
AX5051-1-TA05	7435A													
AX5051-1-TW30	7435A													